

## Malaysia advances semiconductor manufacturing footprint with CHIPX™

**Kuala Lumpur, Malaysia, Thursday 11<sup>th</sup> December** – CHIPX™, a next-generation semiconductor and photonics manufacturer, today announced plans to establish a state-of-the-art, 8-inch wafer fabrication facility in Malaysia, the first of its kind in the ASEAN region. The facility will introduce advanced GaN/SiC manufacturing, driving Malaysia's entry into front-end semiconductor production and accelerating domestic capability in photonics, high-bandwidth optical interconnects, and advanced materials engineering essential to next-generation AI and high-performance compute systems.

CHIPX™ is establishing advanced front-end manufacturing capabilities in Malaysia, spanning infrastructure, R&D, engineering teams, talent development programs, and structured technology-transfer initiatives that build local expertise. Leveraging Malaysia's emerging silicon-photonics ecosystem, CHIPX will provide the fabrication foundation for next-generation transceivers and receivers, enabling ultra-high-speed connectivity for AI data centres and intelligent systems.

*"Malaysia is emerging as a leader in the next wave of semiconductor and photonics innovation,"* said Chinmoy Baruah, CEO and Founder, CHIPX™. *"We are bringing advanced front-end manufacturing and photonics capabilities to Malaysia to accelerate the country's move into front-end semiconductor production and to establish the ultra-high-bandwidth, energy-optimized compute architectures required to scale the next generation of AI systems."*

CHIPX™ is executing the venture with strategic international investors and leading Taiwanese semiconductor partners to bring advanced engineering depth into Malaysia's semiconductor ecosystem. Reflected in this collaboration is CHIPX's long-term commitment to building high-performance, energy optimized front-end semiconductor capabilities in the region.

The project aligns with Malaysia's key industrial policy frameworks – including the National Semiconductor Strategy, the New Industrial Master Plan (NIMP 2030), and the National Energy Transition Roadmap – by supporting national efforts to develop a resilient, competitive, and sustainable semiconductor sector.

### **About CHIPX™**

CHIPX™ is reinventing how and where semiconductors are made. Its vertically integrated platform combines advanced materials, high-voltage ICs, and system-level design to deliver resilient, performance-driven technologies. CHIPX Connect™ accelerates semiconductor innovation across power, photonics and sensing. From ceramic substrates to GaN/SiC ICs,

CHIPX™ enables mission-grade systems for AI, aerospace, and mobility – bridging the gap between R&D and real-world deployment.

*For more information, please visit [chipxglobal.com](https://chipxglobal.com).*

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